

SMD ▪ Low Power LED EAPL2835GA0



Features

- PLCC-2 package
- Top view Green LED
- Wide viewing angle
- Pb-free
- RoHS compliant

Description

The Everlight EAPL2835GA0 package has high efficacy, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- Decorative and Entertainment Lighting
- Agriculture Lighting
- General use

Mass Production List

Product	Wd(nm)	Φ (lm) Min. (2)	Φ (lm) Max. (2)
EAPL2835GA0	515-530	2.5	4.5

Notes:

1. Tolerance of Color Rendering Index: ± 2
2. Tolerance of Luminous flux: $\pm 11\%$.

EVERLIGHT

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Green	Water Clear

Absolute Maximum Ratings (T_{Soldering}=25)

Parameter	Symbol	Rating	Unit
Forward Current	I _F	20	mA
Peak Forward Current (Duty 1/10 @10ms)	I _{FP}	40	mA
Power Dissipation	P _d	78	mW
Operating Temperature	T _{opr}	-40 ~ +85	
Storage Temperature	T _{stg}	-40 ~ +100	
Thermal Resistance (Junction / Soldering point)	R _{th J-S}	50	/W
Junction Temperature	T _j	115	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 Hand Soldering : 350	for 10 sec. for 3 sec.

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics (T_{Soldering}=25)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous flux ⁽¹⁾	Ø	2.5	-----	4.5	lm	I _F =20mA
Forward Voltage	V _F	3.0	-----	3.9	V	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =20mA
Reverse Current	I _R	-----	-----	50	µA	V _R =5V

Notes:

1. Tolerance of Radiometric Luminous flux: ±11%.
2. Tolerance of Forward Voltage: ±0.1V.

Bin Range of Photometric

Bin Code	Min.	Max.	Unit	Condition
D5	2.5	3.0	lm	I _F =20mA
D6	3.0	3.5		
D7	3.5	4.0		
D8	4.0	4.5		

Notes:
Tolerance of Luminous flux: ±11%

Bin Range of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
30B	3.0	3.2	V	I _F =20mA
32B	3.2	3.4		
34B	3.4	3.6		
36B	3.6	3.8		
45	3.8	3.9		

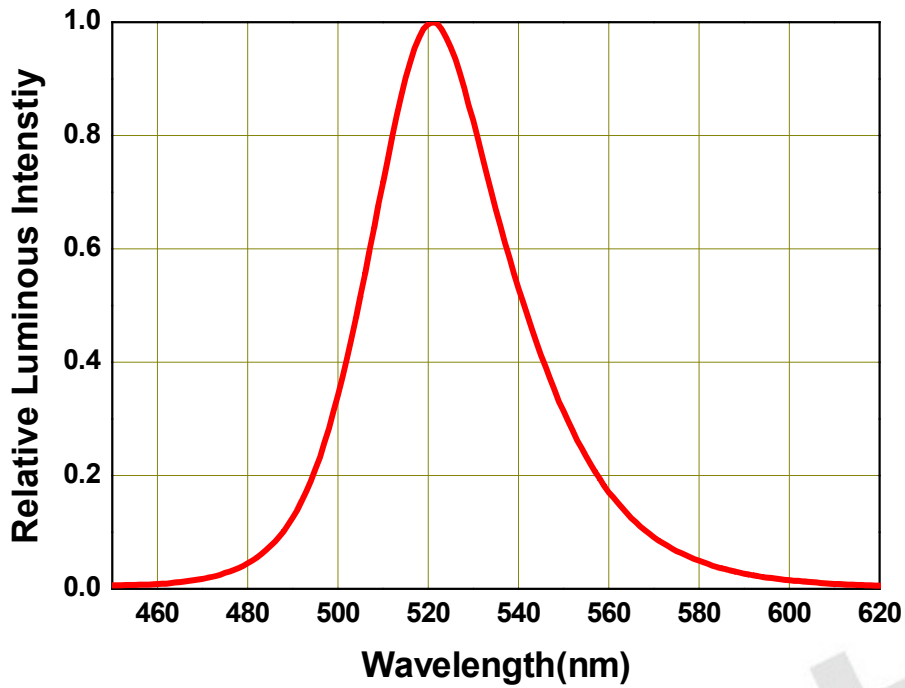
Note:
Tolerance of Forward Voltage: ±0.1V.

Dominant Wavelength Bins

Bin Code	Min.	Max.	Unit	Condition
G51	515	520	nm	I _F =20mA
G52	520	525		
G53	525	530		

Notes:
Dominant / Peak wavelength measurement tolerance: ±1nm.

Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 – Forward Voltage Shift vs. Junction Temperature

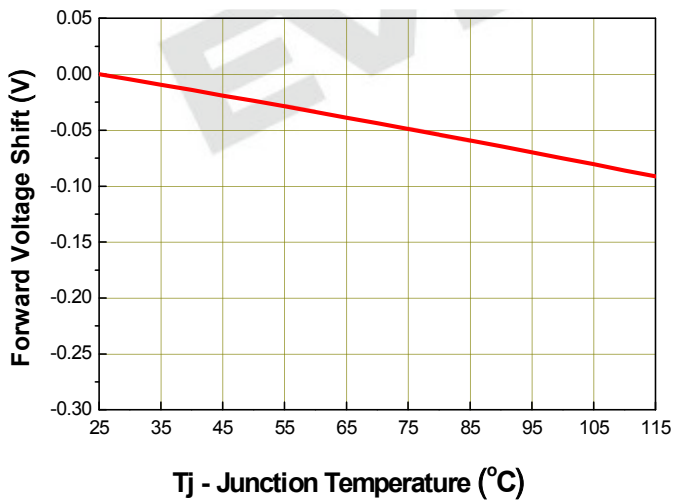
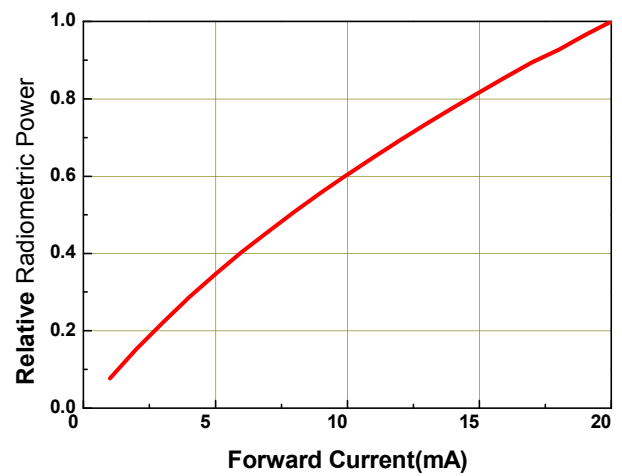


Fig.2 - Relative Radiometric Power vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

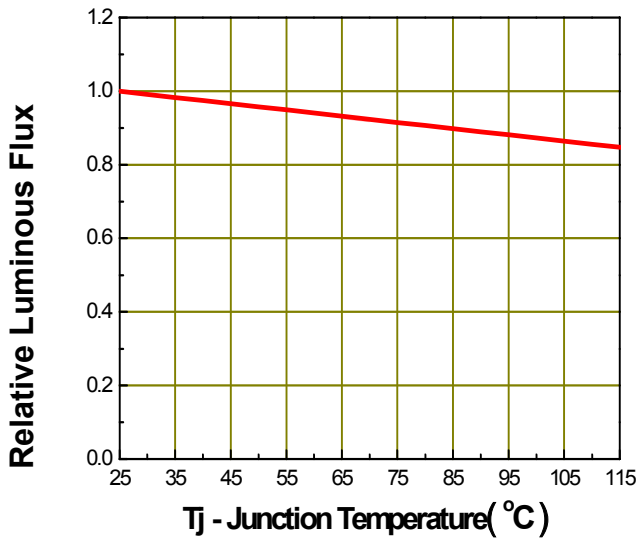


Fig.4 - Forward Current vs. Forward Voltage

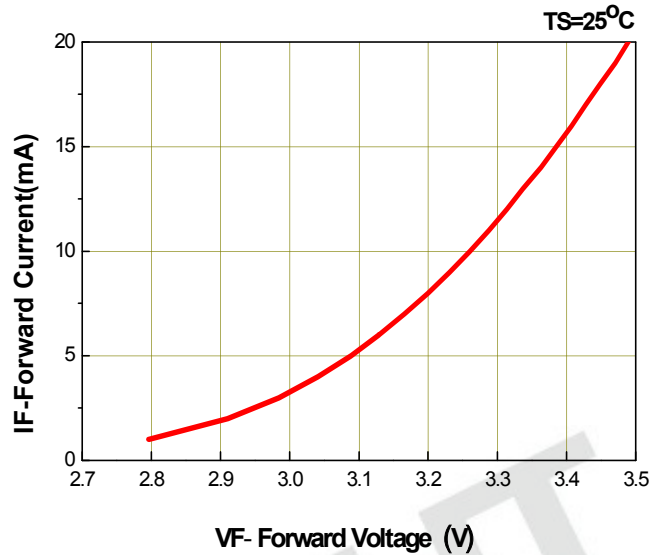


Fig.5 – Max. Driving Forward Current vs. Soldering Temperature

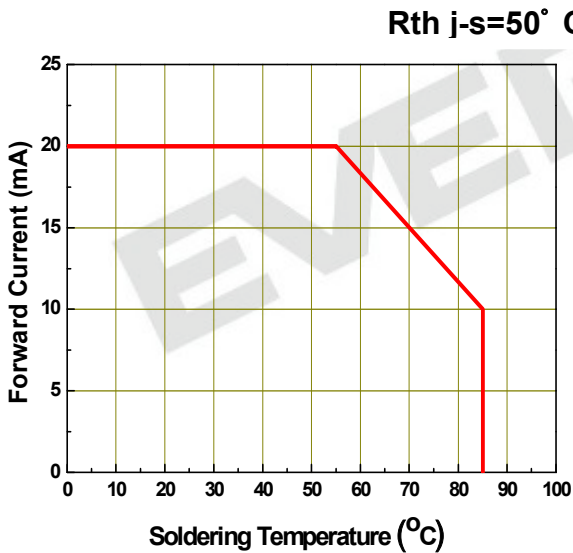
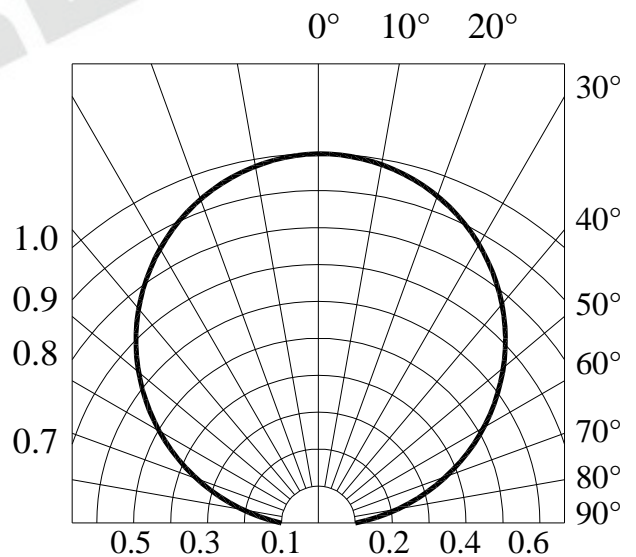
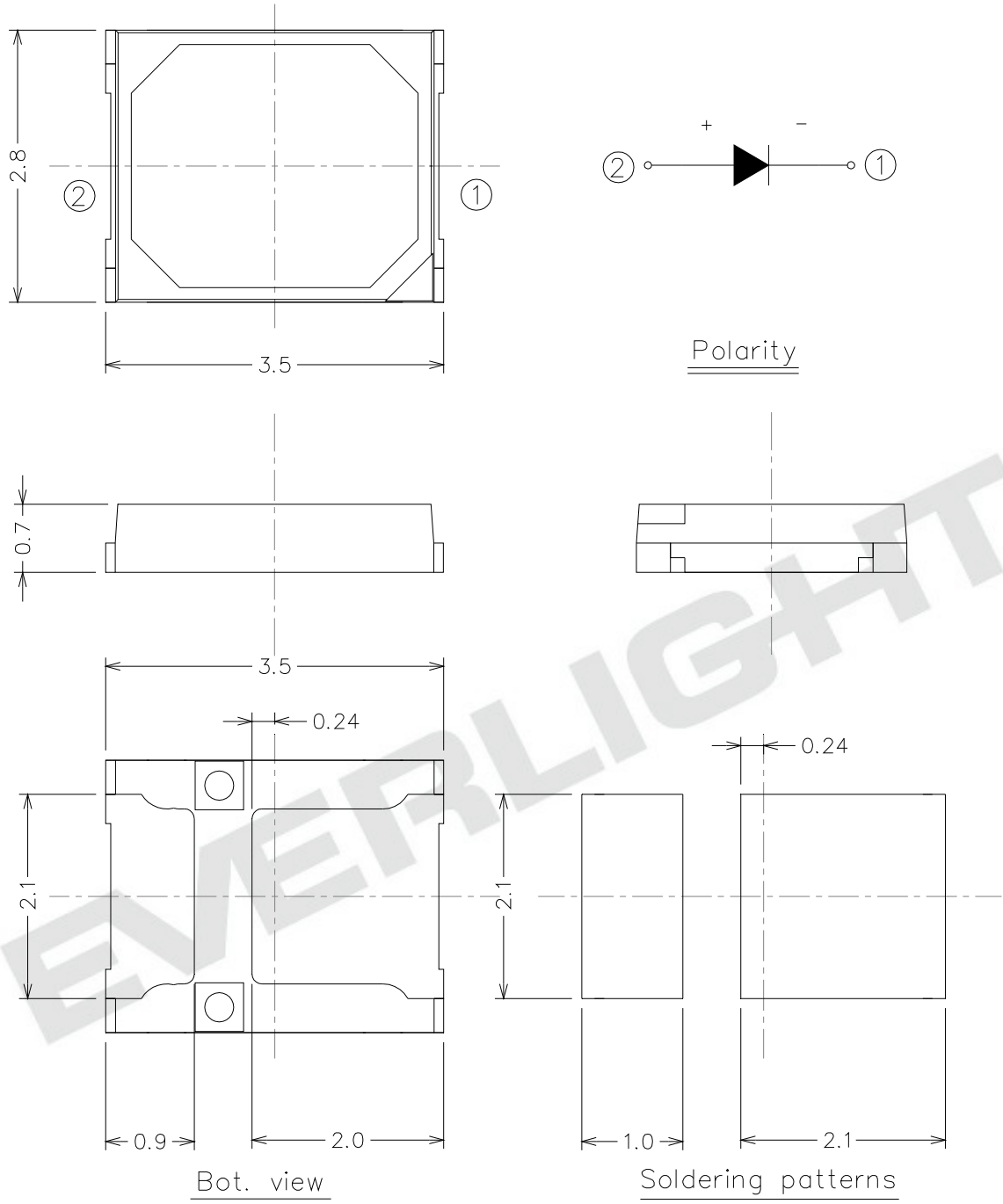


Fig.6 – Radiation Diagram



Package Dimension



Note:
Tolerance unless mentioned is ± 0.15 mm; Unit = mm

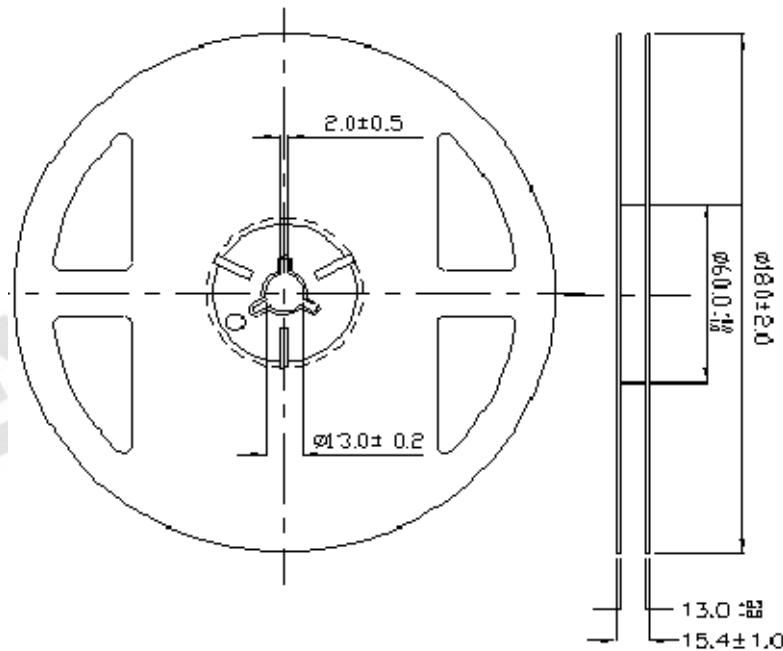
Moisture Resistant Packing Materials

Label Explanation



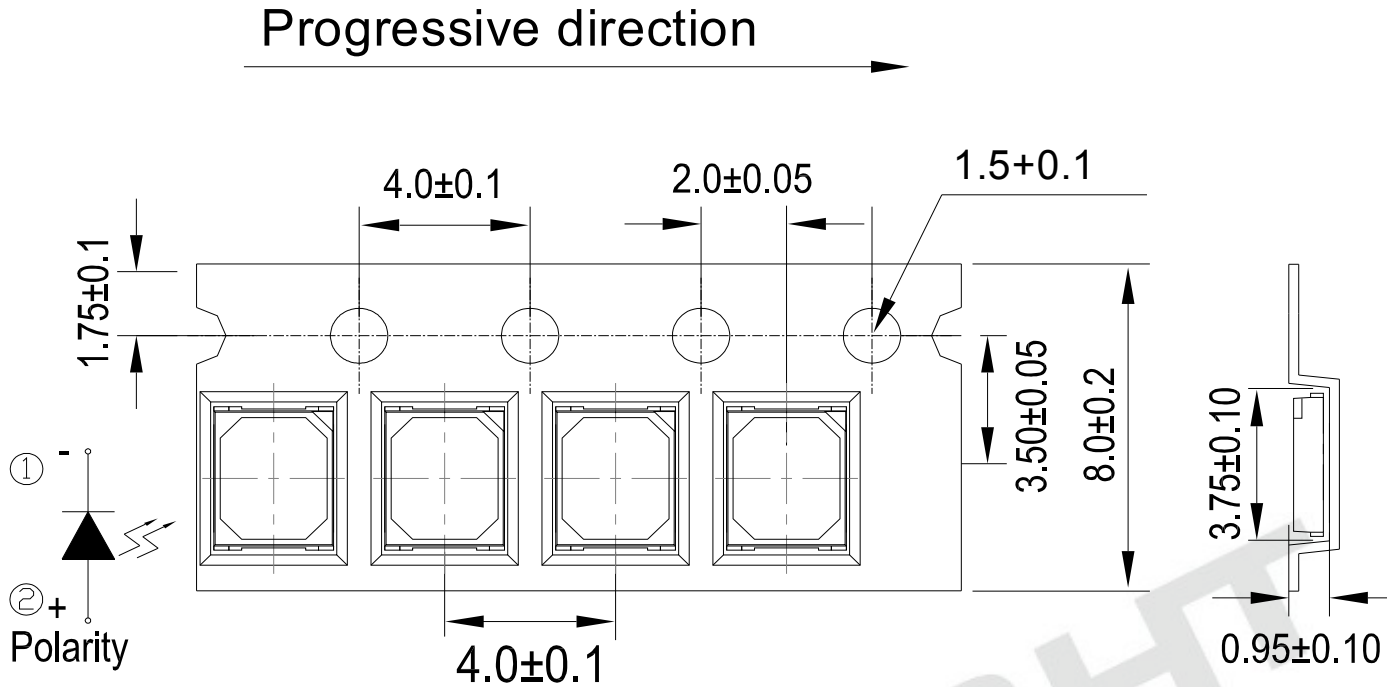
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



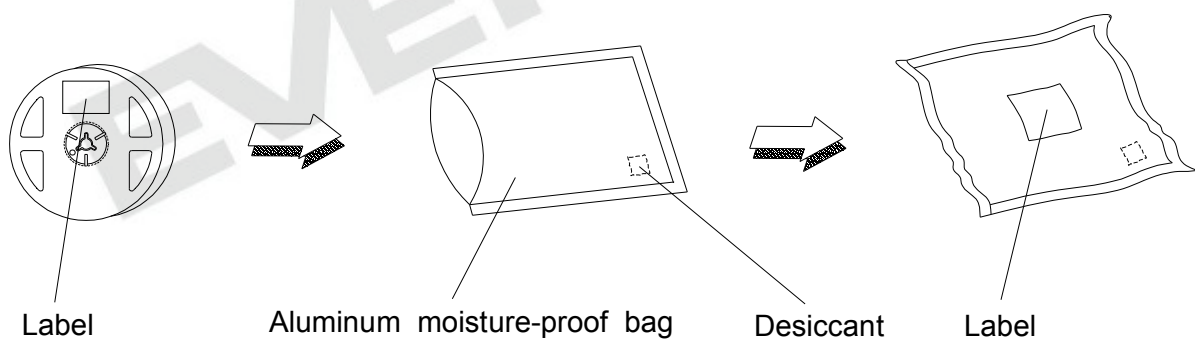
Note:
 Tolerances unless mentioned ± 0.1 mm. Unit = mm

Carrier Tape Dimensions: Loaded Quantity 2000 pcs. Per Reel



Note:
 Tolerance unless mentioned is ± 0.1 mm; Unit = mm

Moisture Resistant Packing Process



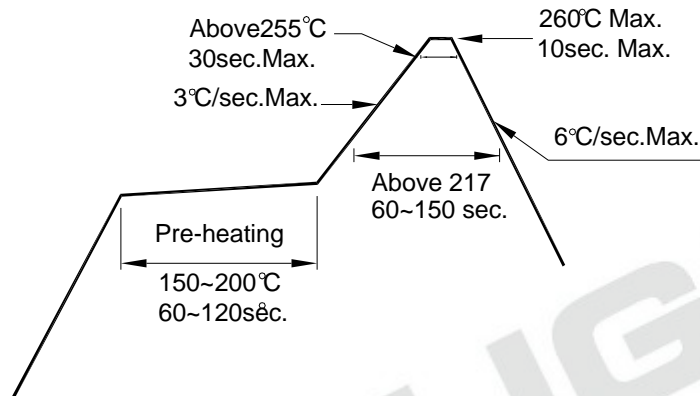
Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level : 90%
LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260 /10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100 20min 10 sec L : -10 20min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100 30min 5 min L : -40 30min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Storage	Ta=85 ,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85 ,85%RH, I _F = 10mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40 , I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25 , I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55 , I _F =20mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85 , I _F = 10 mA	1000 Hrs.	22 PCS.	0/1

Precautions for Use

1. Over-current-proof
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30 or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30 or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment: 60 ± 5 for 24 hours.
3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
4. Soldering Iron
Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.
5. Repairing
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

